

To our customers,

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## Old Company Name in Catalogs and Other Documents

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Renesas Electronics website: <http://www.renesas.com>

April 1<sup>st</sup>, 2010  
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (<http://www.renesas.com>)

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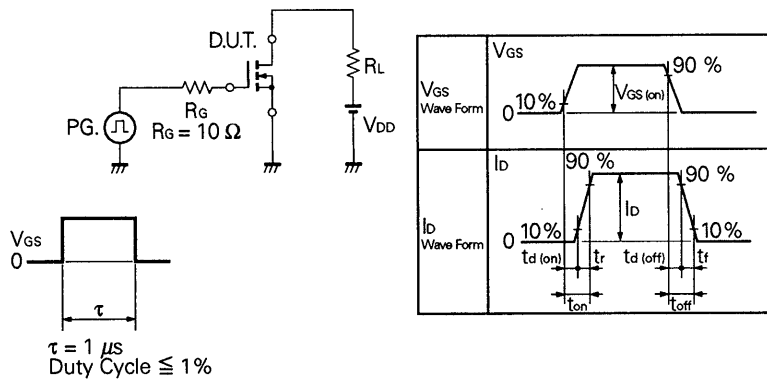
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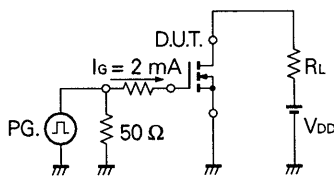
**ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)**

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Drain to Source On-state Resistance	R <sub>DS(on)</sub>		0.08	0.11	Ω	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4 A
Drain to Source On-state Resistance	R <sub>DS(on)</sub>		0.11	0.16	Ω	V <sub>GS</sub> = 4 V, I <sub>D</sub> = 4 A
Gate to Source Cutoff Voltage	V <sub>GS(off)</sub>	1.0		2.5	V	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA
Forward Transfer Admittance	y <sub>fs</sub>	5.0			S	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 4 A
Drain Leakage Current	I <sub>DSS</sub>			10	μA	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0
Gate to Source Leakage Current	I <sub>GSS</sub>			±10	μA	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0
Input Capacitance	C <sub>iss</sub>		850		pF	V <sub>DS</sub> = 10 V
Output Capacitance	C <sub>oss</sub>		350		pF	V <sub>GS</sub> = 0
Reverse Transfer Capacitance	C <sub>rss</sub>		100		pF	f = 1 MHz
Turn-On Delay Time	t <sub>d(on)</sub>		15		ns	V <sub>GS(on)</sub> = 10 V V <sub>DD</sub> = 30 V I <sub>D</sub> = 4 A, R <sub>G</sub> = 10 Ω R <sub>L</sub> = 7.5 Ω
Rise Time	t <sub>r</sub>		60		ns	
Turn-Off Delay Time	t <sub>d(off)</sub>		100		ns	
Fall Time	t <sub>f</sub>		45		ns	
Total Gate Charge	Q <sub>G</sub>		3		nC	V <sub>GS</sub> = 10 V I <sub>D</sub> = 8 A V <sub>DD</sub> = 48 V
Gate to Source Charge	Q <sub>GS</sub>		7		nC	
Gate to Drain Charge	Q <sub>GD</sub>		25		nC	
Reverse Recovery Time	t <sub>rr</sub>		120		ns	I <sub>F</sub> = 8 A, V <sub>GS</sub> = 0
Reverse Recovery Charge	Q <sub>rr</sub>		200		nC	di/dt = 50 A/μs

**Test Circuit 1: Switching Time**

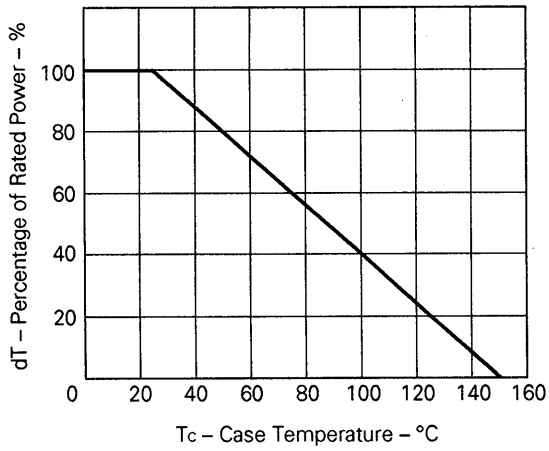


**Test Circuit 2: Gate Charge**

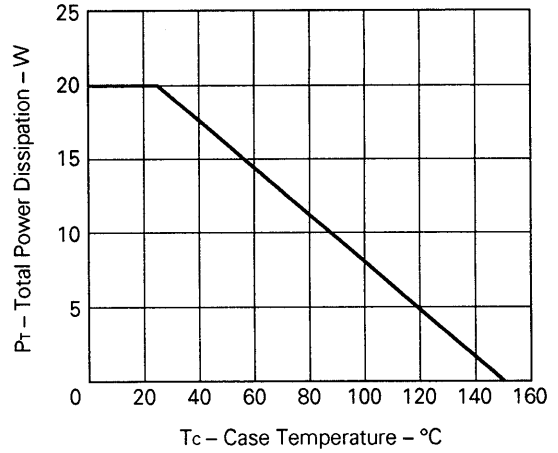


TYPICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

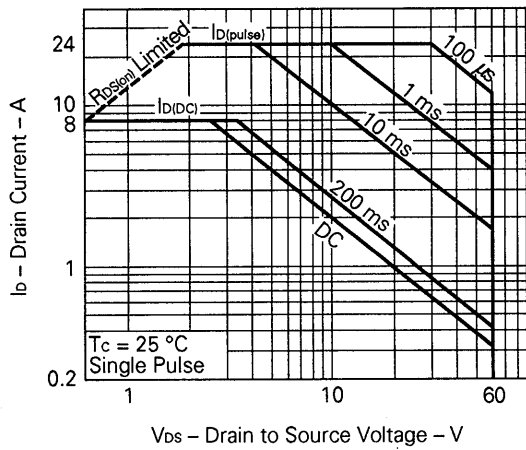
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



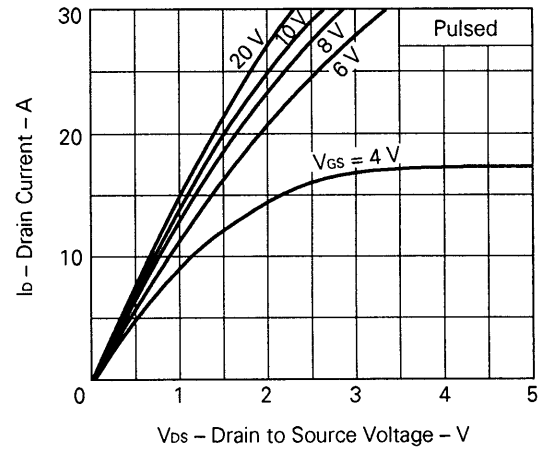
TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



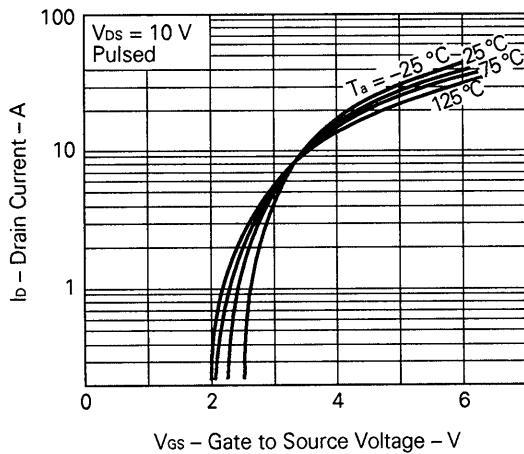
FORWARD BIAS OPERATING AREA



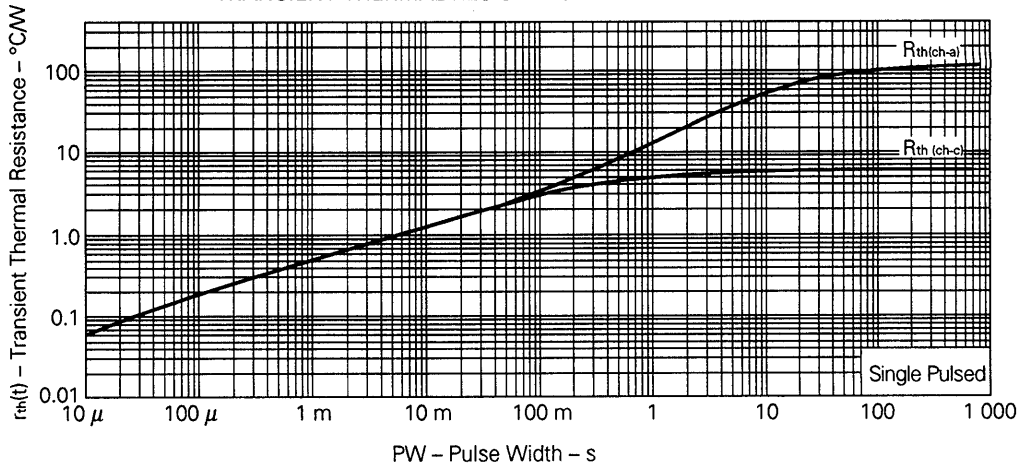
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



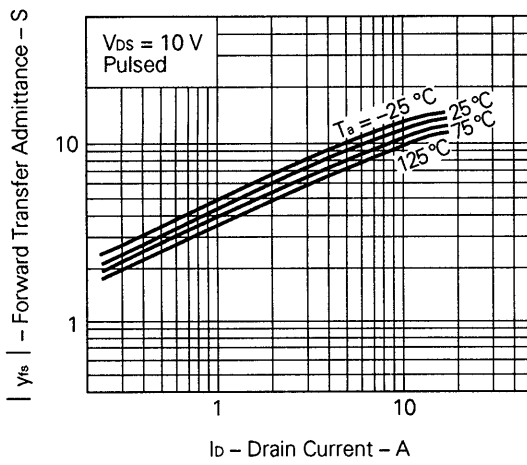
TRANSFER CHARACTERISTICS



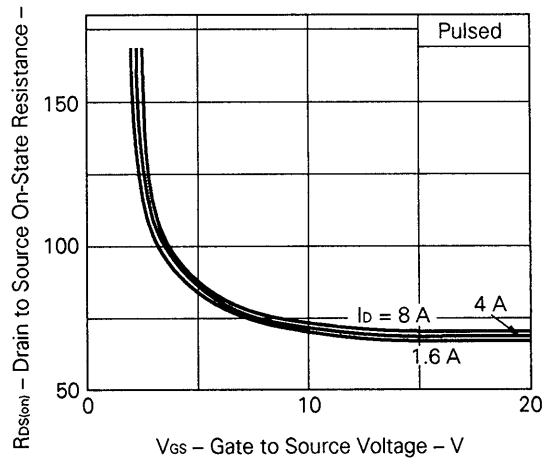
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



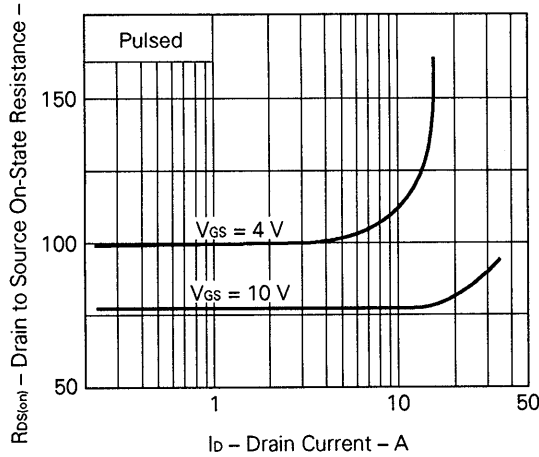
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



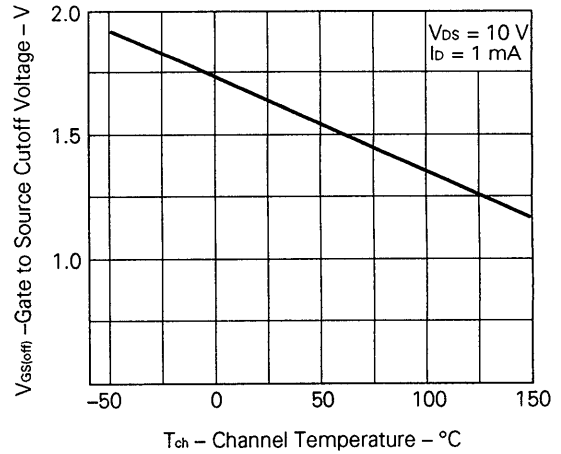
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



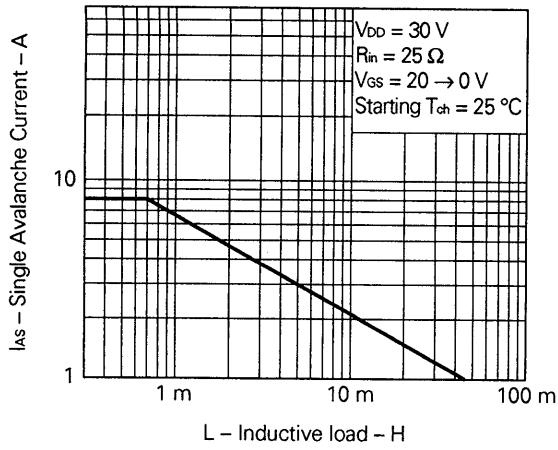
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



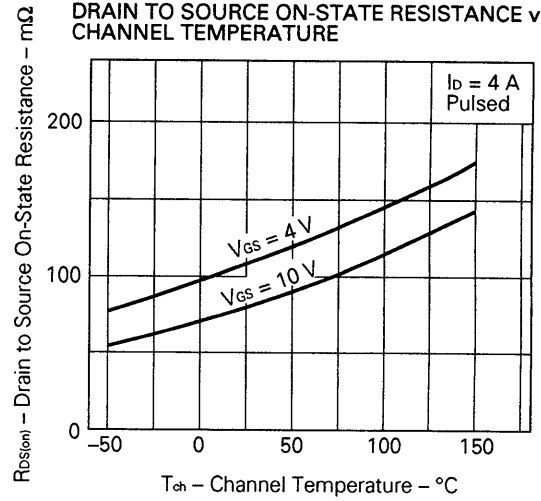
GATE TO SOURCE CUTOFF VOLTAGE vs. CHANNEL TEMPERATURE



SINGLE AVALANCHE CURRENT vs. INDUCTIVE LOAD



DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE





**Reference**

Application note name	No.
Safe operating area of Power MOS FET.	TEA-1034
Application circuit using Power MOS FET.	TEA-1035
Quality control of NEC semiconductors devices.	TEI-1202
Quality control guide of semiconductors devices.	MEI-1202
Assembly manual of semiconductors devices.	IEI-1207

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